

REMARKS

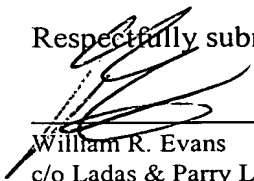
Inasmuch as the present Action is on the wrong claims, THE EXAMINER IS REQUESTED TO TELEPHONE THE UNDERSIGNED WHEN HE CONSIDERS THIS Request and Amendment to make sure that the application may again progress.

The stacked semiconductor chip package disclosed by Maeda (JP03109760) comprising a lead frame 12 (not a substrate), a first chip 8, a second chip 4 and an insulation film 12 (as shown in FIG. 2), wherein the second chip 4 is attached to the top surface of the lead frame 12, the insulation film 12 is attached to the bottom surface of the lead frame 12, and the first chip 8 is attached to the insulation film 12. In comparison, the stacked semiconductor chip package of the present invention comprises a substrate 21, a first chip 22, a second chip 24, and a plate 23 (as shown in FIGs.. 2a to 2c), wherein the first chip 22 is attached to the top surface of the substrate 21, the second chip 24 is disposed above the first chip 22, and the plate 23 is disposed between the first chip 22 and the second chip 24 and adheres to the first chip 22 and the second chip 24 by an adhesive layer 25. Therefore, the structure of the present invention is very different from that of the citation.

In addition, Maeda does not disclose the characteristic of "the portion of the plate 23 under the second chip 24 is wrapped by the adhesive layer 25, and the adhesive layer 25 is exposed at the corner formed by the plate 23 and the second chip 24 along the longitudinal side of the plate 23," which is the major characteristic for achieving the objective of detecting the size of the overflow adhesive portion 26 and the thickness of the adhesive layer 25.

Reconsideration and allowance are, therefore, requested.

Respectfully submitted,



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